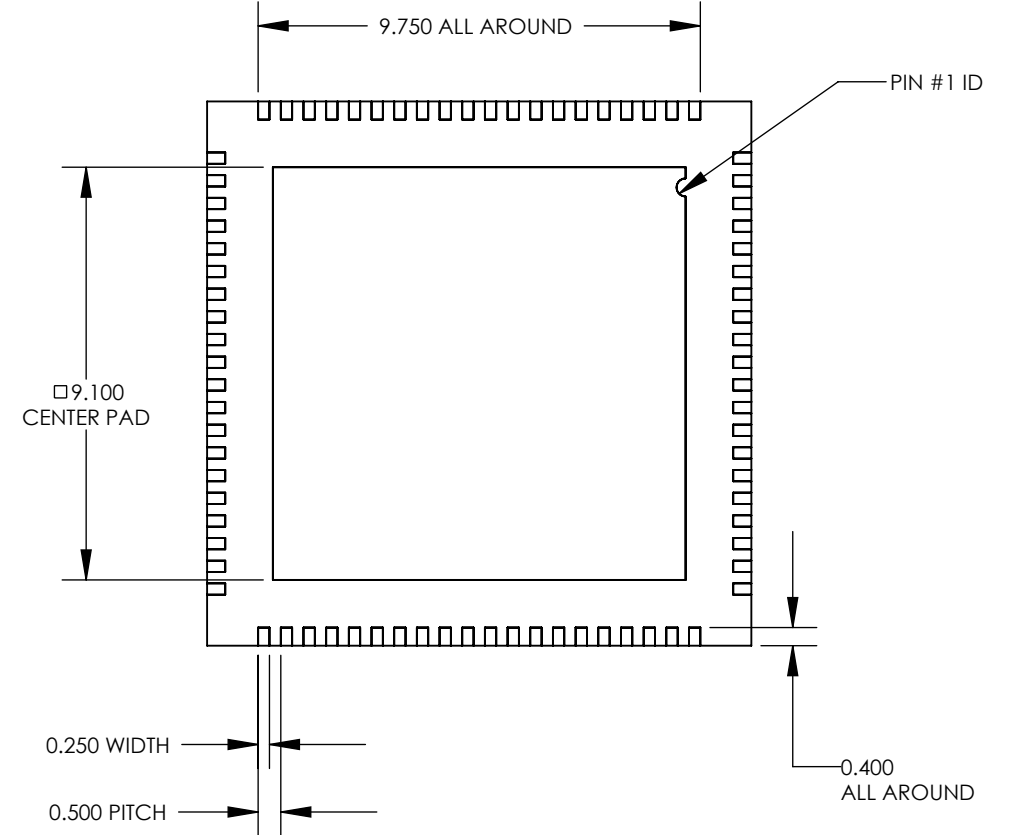
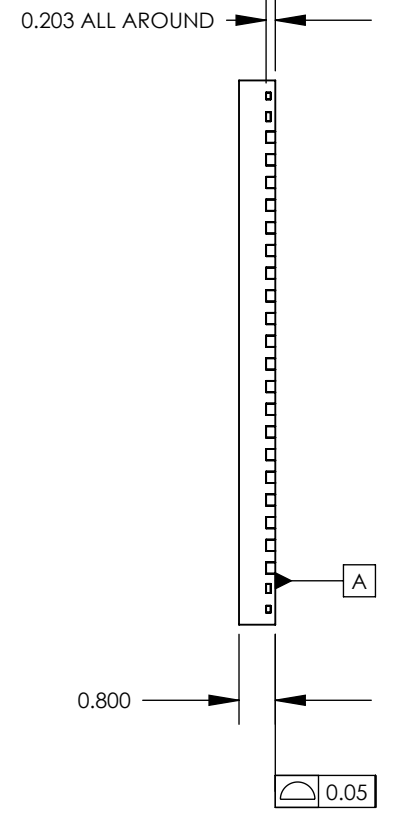
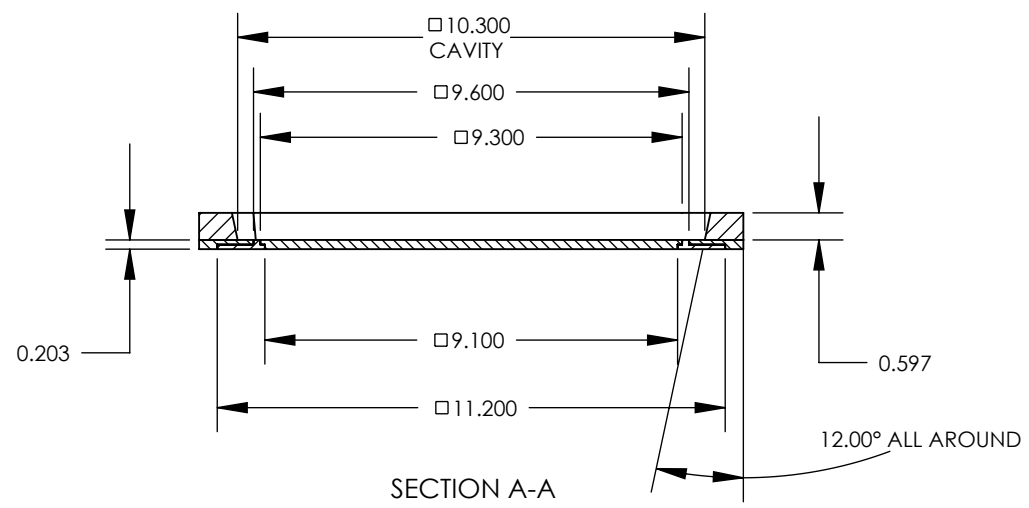


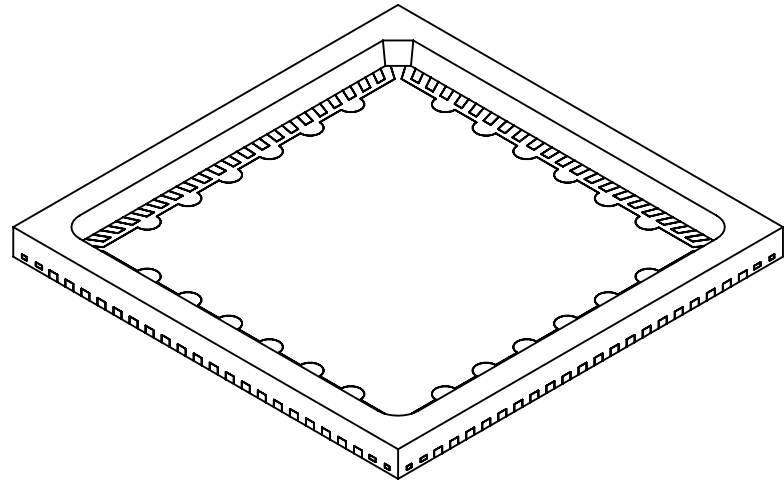
TOP VIEW



BOTTOM VIEW



SECTION A-A



NOTES

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220

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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		NAME	DATE	TITLE: QP-QFN80-12MM-0.50MM
		ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		DRAWN	D. Abbe 8/11/11	
				CHECKED	S. Swen 8/11/11	
				ENG APPR.	S. Swen 8/11/11	SIZE B
				COMMENTS:		
		MATERIAL SEE NOTE 1				DWG. NO. 500410
		FINISH SEE NOTE 2				REV A
NEXT ASSY	USED ON					SCALE: 6:1
APPLICATION		DO NOT SCALE DRAWING				WEIGHT:
						SHEET 1 OF 1